

Fig. 1

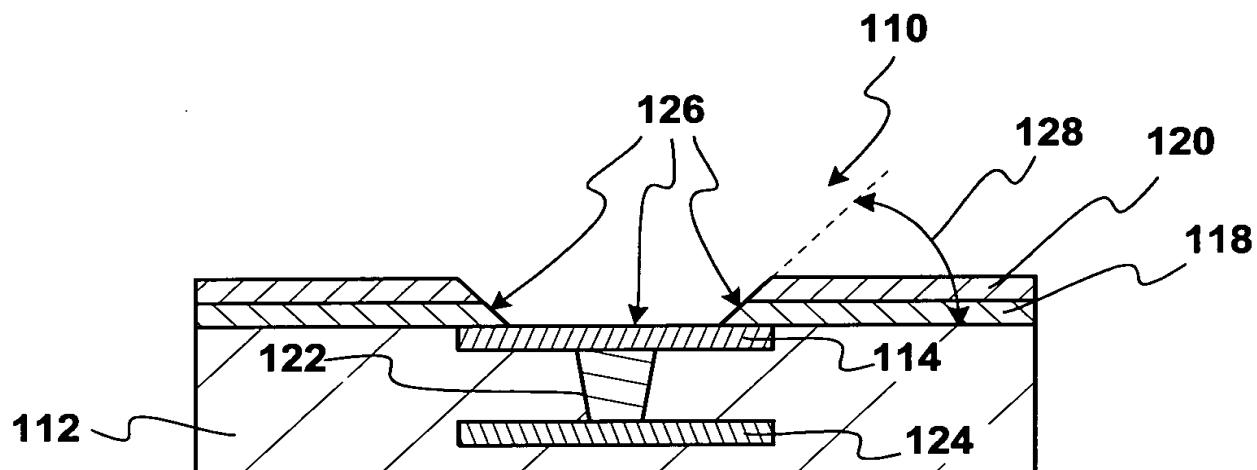


Fig. 2



TITLE: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-MG  
INVENTORS NAME: Krishna Seshan et al.  
SERIAL NO.: 10/052089

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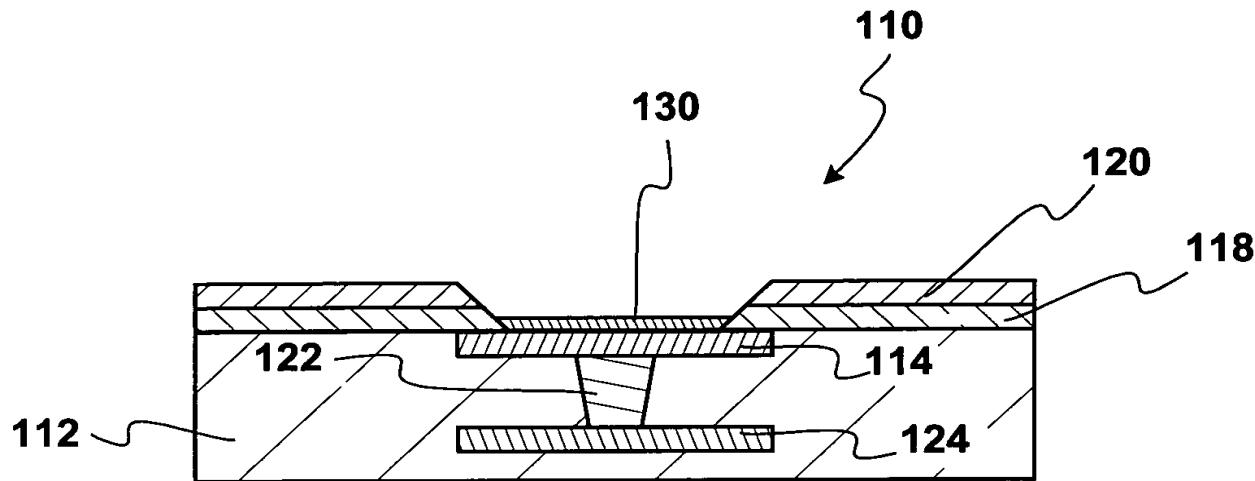


Fig. 3

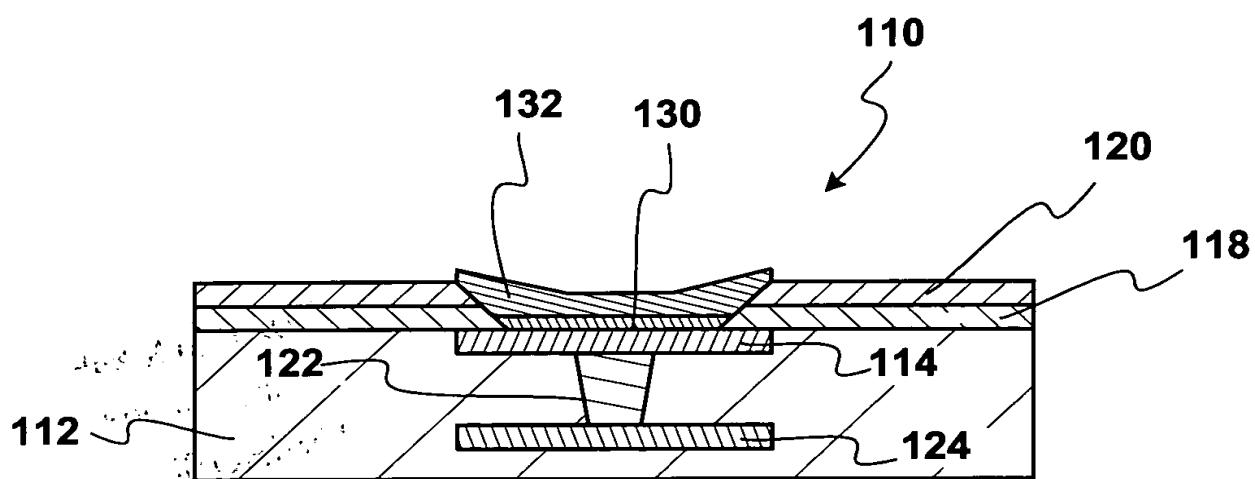


Fig. 4



TITLE: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6  
INVENTORS NAME: Krishna Seshan et al.  
SERIAL NO.: 10/052089

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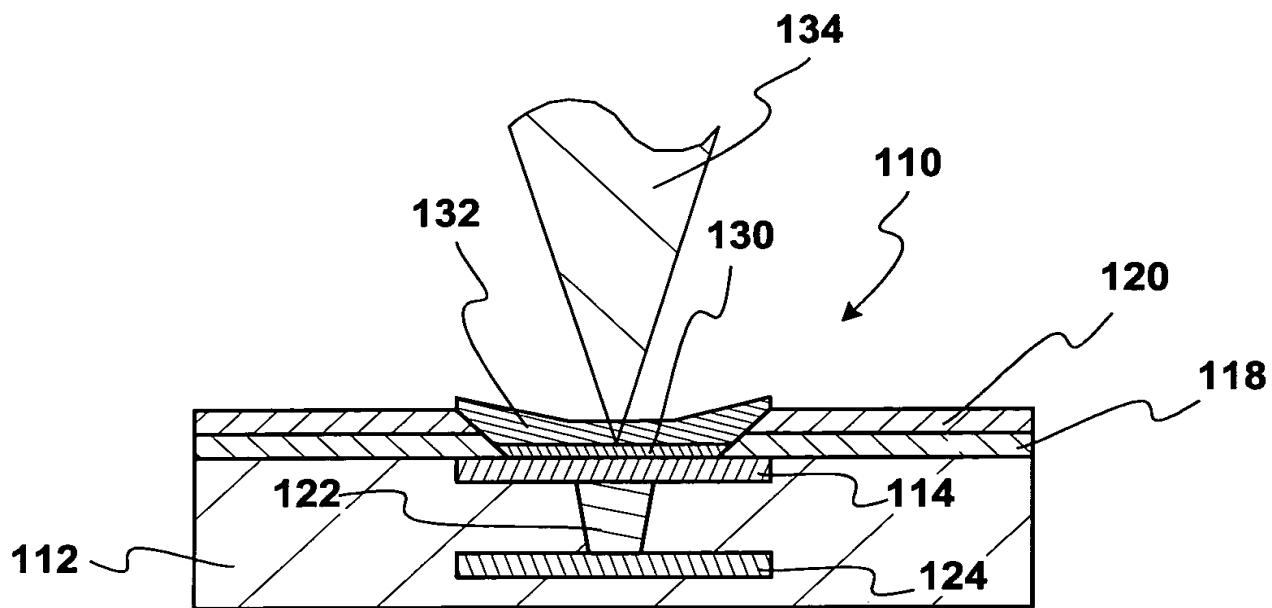


Fig. 5

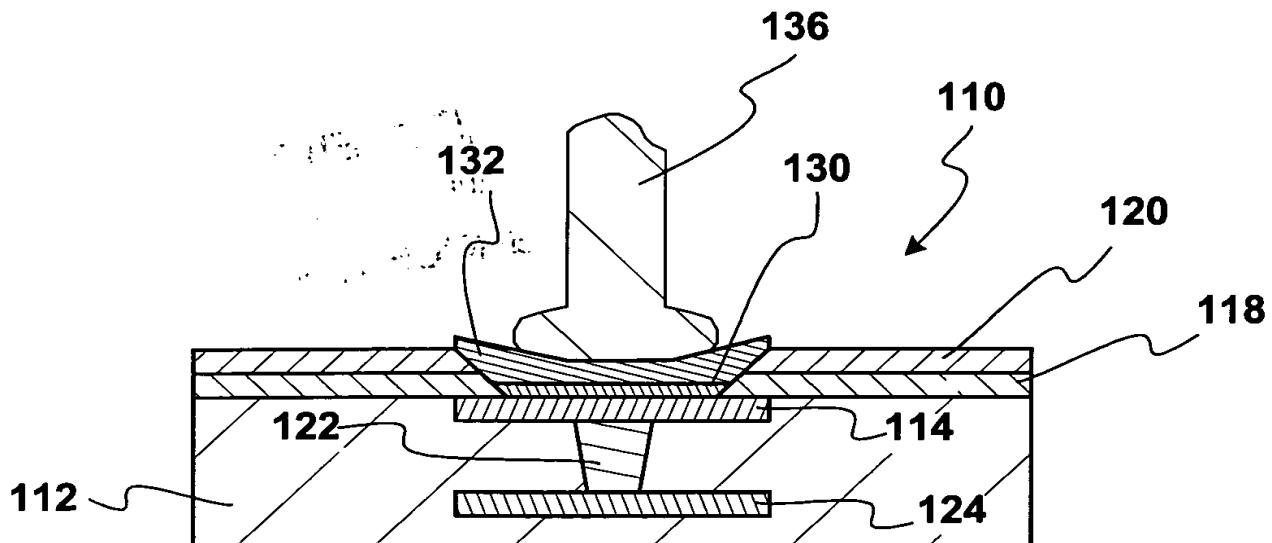


Fig. 6

TITLE: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6  
INVENTORS NAME: Krishna Seshan et al.  
SERIAL NO.: 10/052089

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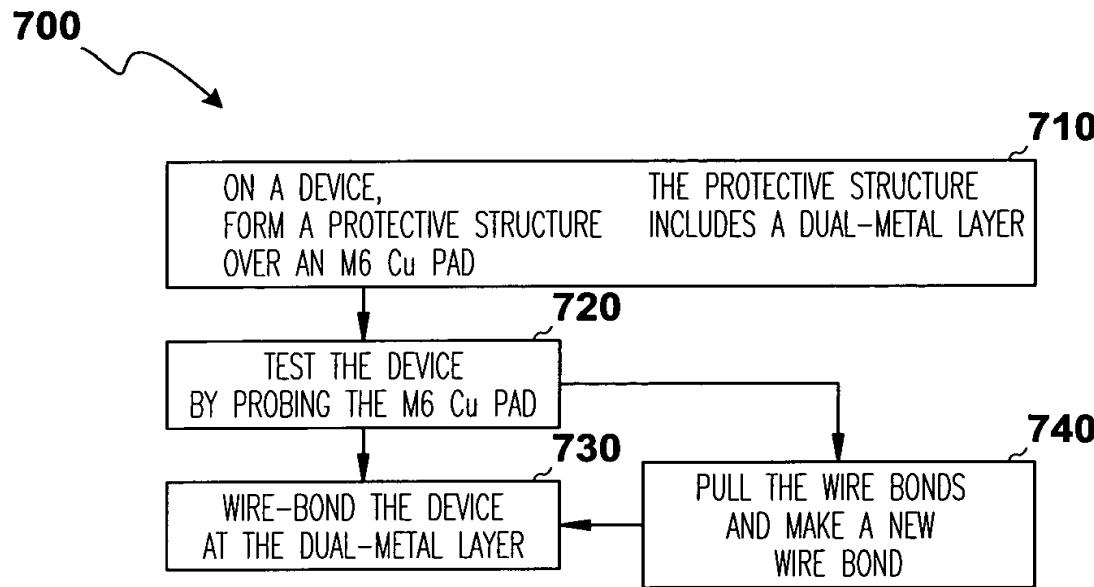


Fig. 7

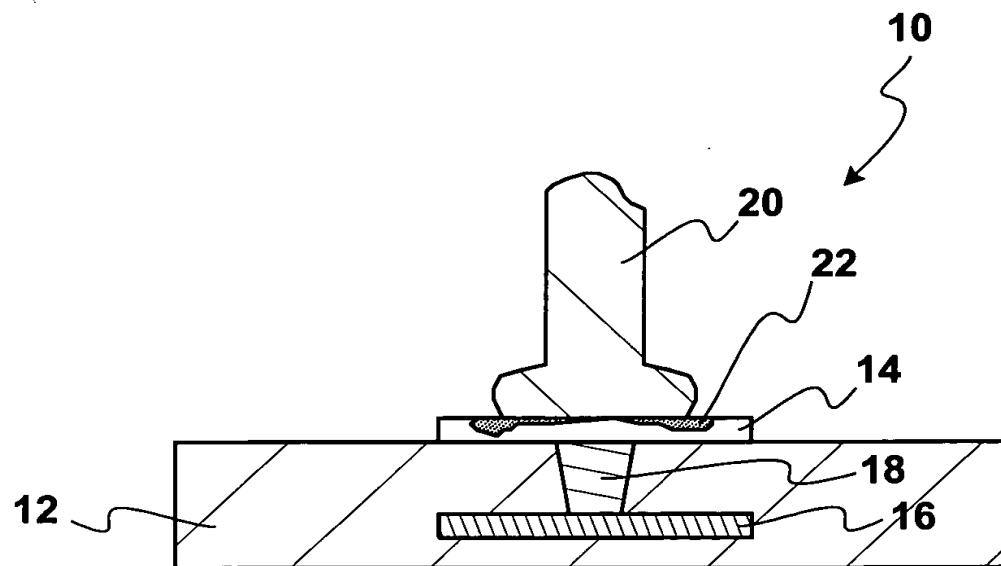


Fig. 8  
(Prior Art)